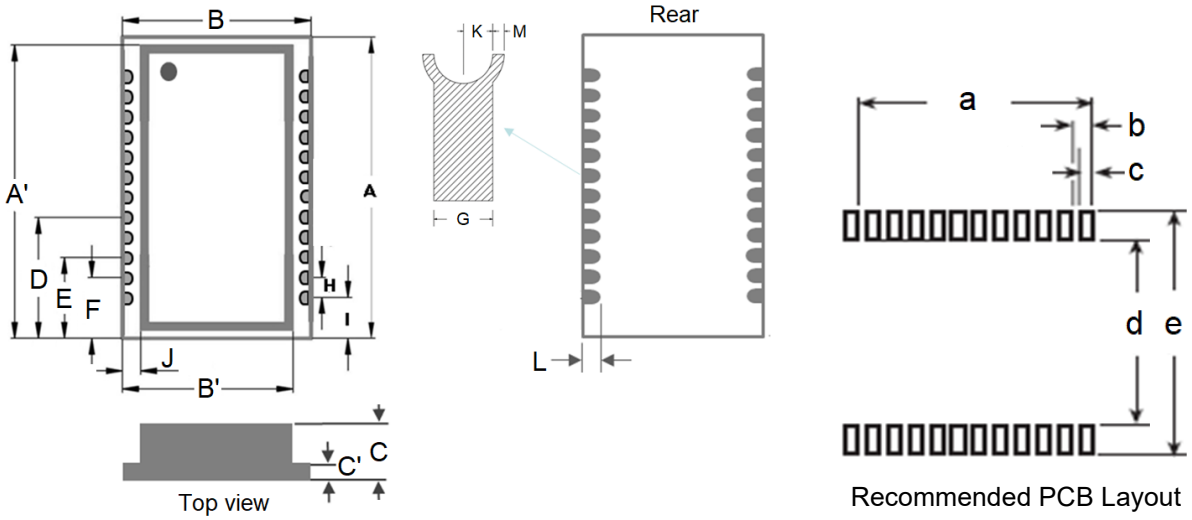
1. Part No. Expression

S L T 1 7 1 4 4 5 G 2 4 1 P 7 B 8

(a) (b) (c) (d) (e)

(a) Series Code
(b) Dimension Code
(c) Material Code
(d) Pin Code
(e) Control Code

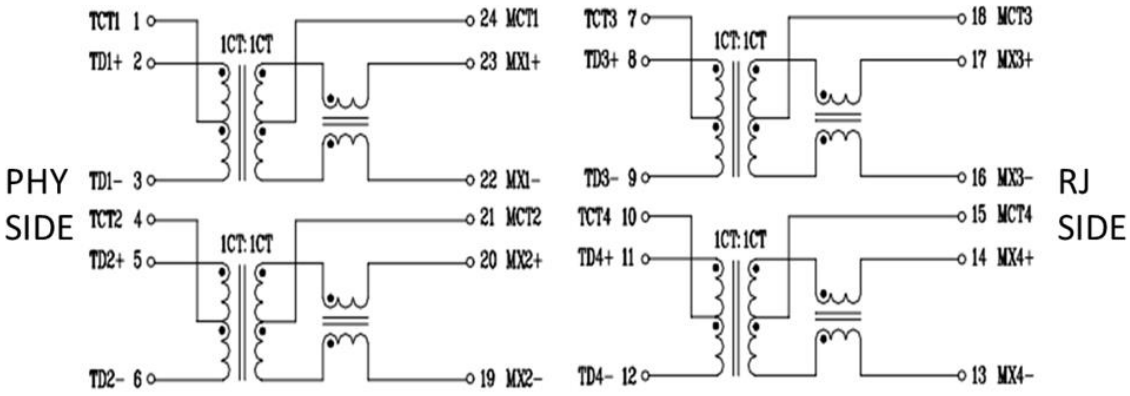
2. Configuration & Dimensions (Unit: mm)



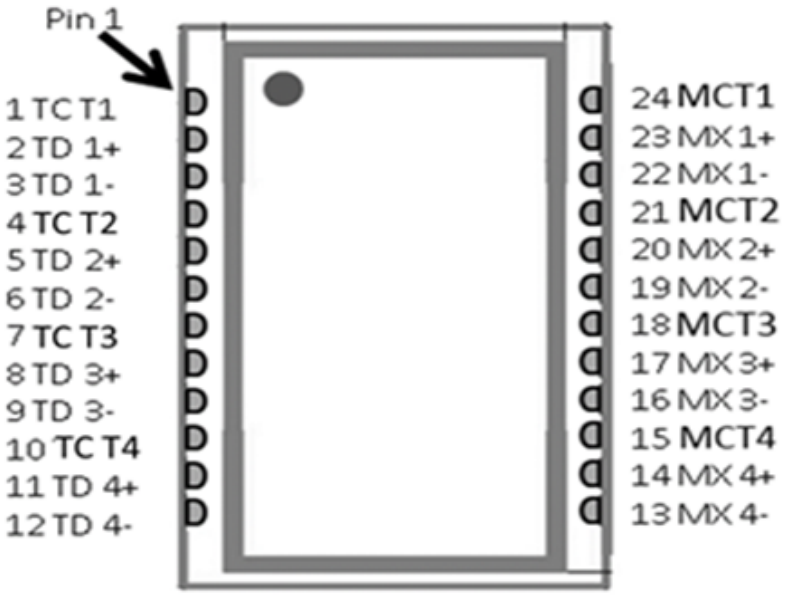
A	A’	B	B’	C	C’	D
17.530±0.250	17.030±0.250	14.600±0.250	13.920±0.250	4.500 Max.	1.000±0.250	6.860±0.250
E	F	G	H	I	J	K
4.320±0.250	3.050±0.250	0.400±0.150	1.270±0.150	1.780±0.250	0.670±0.150	0.200±0.075
L	M	a	b	c x 24	d	e
1.100±0.150	0.095±0.076	13.970±0.250	1.270±0.250	0.760±0.050	12.700±0.250	16.510±0.250

NOTE: Specifications subject to change without notice. Please check our website for latest information.

3. Schematic



4. Pin Define



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5. General Specifications

(a) Operating Temp.: -40°C to +85°C (including self-temperature rise)

(b) Storage Temp.: -40°C to +85°C (on board)

(c) Humidity Range: 85±2% RH

(d) Hi- Pot Resistance Test: 1500 VAC for 1 minute

(e) Storage Condition (Component in its packaging)

i) Temperature: Less than 40°C

ii) Humidity: Less than 60% RH

6. Electrical Characteristics

Insertion Loss (dB) Max	Return Loss (dB) Min					Cross talk (dB) Min	DCMR (dB) Min	
1~100MHz	1~30MHz	40MHz	50MHz	60~80MHz	100MHz	1~100MHz	1~60MHz	60~100MHz
-1.1	-18	-14.4	-13.1	-12	-10	-35	-35	-30

NOTE: Specifications subject to change without notice. Please check our website for latest information.

7. Soldering Specification

Mildly activated rosin fluxes are preferred. Our terminations are suitable for re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

7-1. IR Soldering Reflow

Recommended temperature profiles for lead free re-flow soldering in Figure 1, Table 1.1 & 1.2 (J-STD-020E).

7-2. Iron Reflow

Products attachment with a soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended (Figure 2).

Note:

(a) Preheat circuit and products to 150°C.

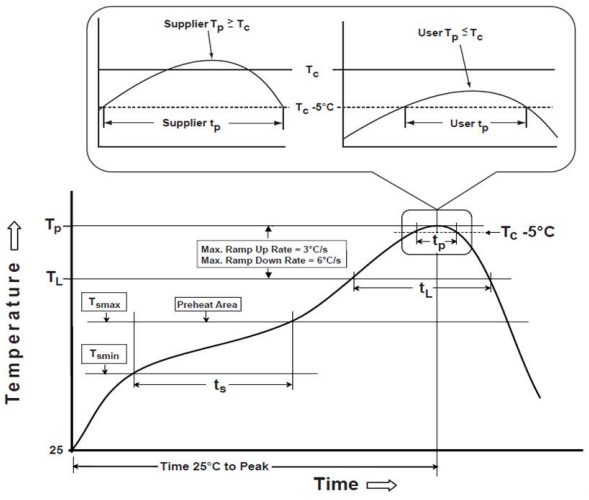
(b) 355°C tip temperature (Max.)

(c) Never contact the ceramic with the iron tip

(d) 1.0mm tip diameter (Max.)

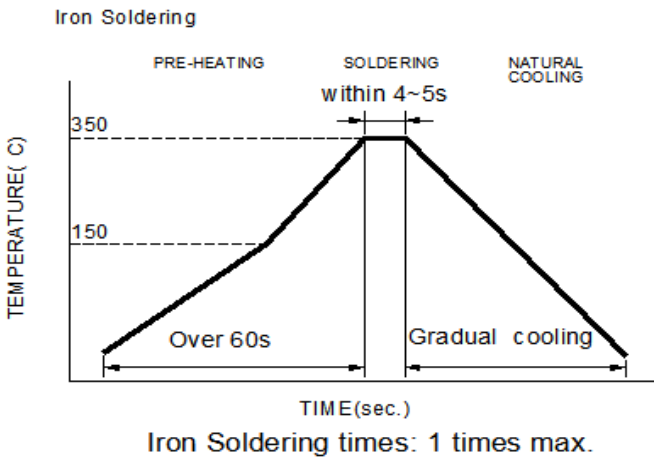
(e) Use a 20 watt soldering iron with tip diameter of 1.0mm

(f) Limit soldering time to 4~5 sec.



Reflow times: 3 times Max

Figure 1: IR Soldering Reflow



Soldering iron method: 350±5°C Max

Figure 2: Iron soldering temperature profiles

NOTE: Specifications subject to change without notice. Please check our website for latest information.

Table (1.1) Reflow Profiles

Profile Type:	Pb-Free Assembly
Preheat -Temperature Min (T_{smin}) -Temperature Max (T_{smax}) -Time (t_s) from (T_{smin} to T_{smax})	 150°C 200°C 60-120seconds
Ramp-up rate ($T_L$to T_p)	3°C /second max.
Liquids temperature (T_L) Time (t_L) maintained above T_L	217°C 60-150 seconds
Classification temperature (T_c)	See Table (1.2)
Time (t_p) at Tc- 5°C (Tp should be equal to or less than Tc.)	*< 30 seconds
Ramp-down rate (T_p to T_L)	6°C /second max.
Time 25°C to peak temperature	8 minutes max.

Tp: maximum peak package body temperature, **Tc**: the classification temperature.

For user (customer) **Tp** should be equal to or less than **Tc.**

*Tolerance for peak profile temperature (Tp) is defined as a supplier minimum and a user maximum.

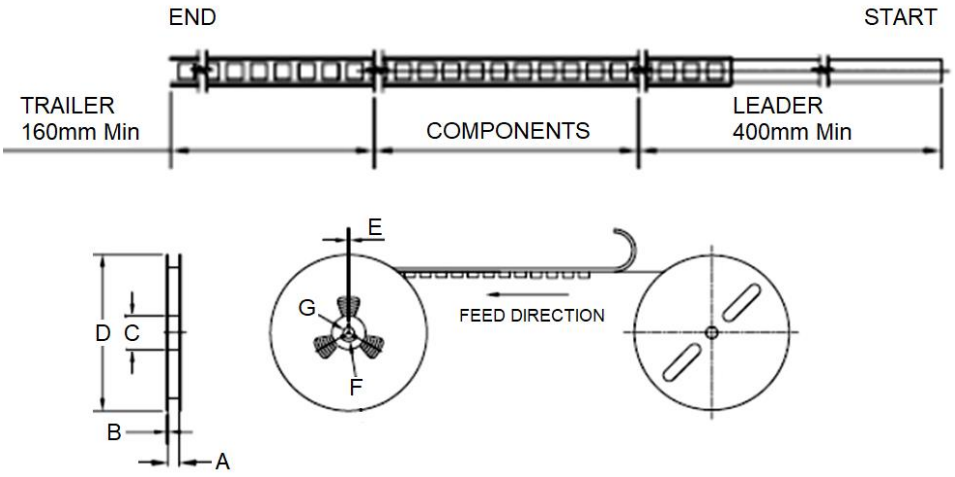
Table (1.2) Package Thickness/Volume and Classification Temperature (T_c)

	Package Thickness	Volume mm^3 <350	Volume mm^3 350-2000	Volume mm^3 >2000
PB-Free Assembly	<1.6mm	260°C	260°C	260°C
	1.6-2.5mm	260°C	250°C	245°C
	≥2.5mm	250°C	245°C	245°C

Reflow is referred to standard IPC/JEDEC J-STD-020E.

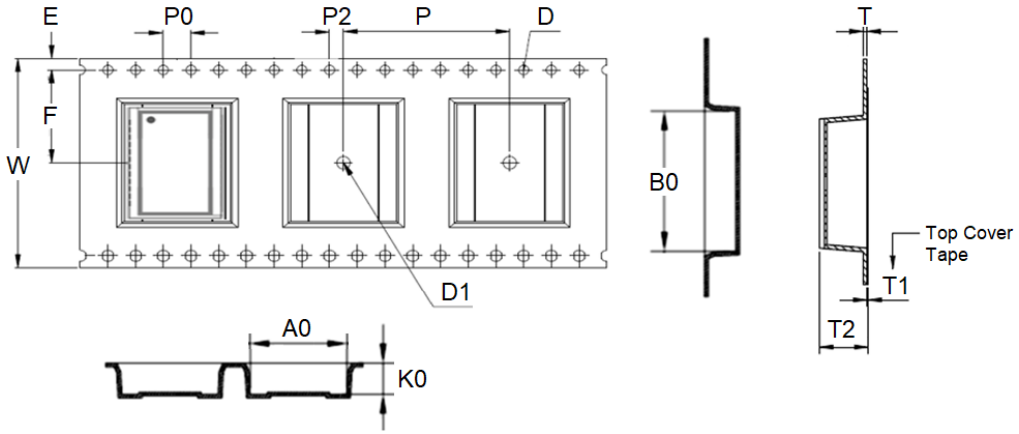
8. Packaging Information

8-1. Reel Dimension (Unit: mm)



Type	A	B	C	D	E	F	G
13”x32mm	33.5 Ref	2.0 Ref	100.0 Ref	330 Ref	2.5 Ref	∅ 21.5 Ref	∅ 13.0 Ref

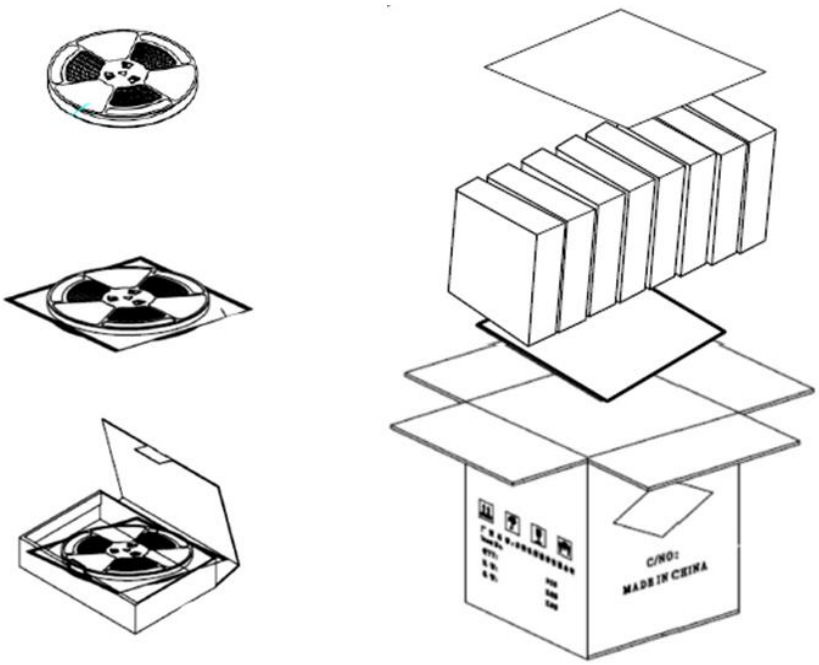
8-2. Tape Dimension (Unit: mm)



B0	A0	K0	P	P0	P2	W
17.93±0.10	15.30±0.10	4.80±0.10	24.00±0.10	4.00±0.10	2.00±0.10	32.00±0.30
F	D	D1	T	T1	T2	E
14.20±0.10	1.50±0.10	1.50	0.40±0.05	0.06±0.01	5.60±0.10	1.75±0.10

NOTE: Specifications subject to change without notice. Please check our website for latest information.

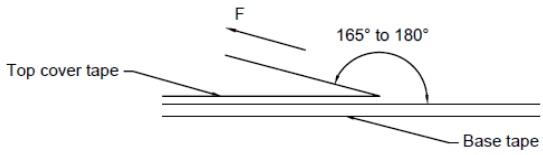
8-3. Packaging Type



8-4. Packaging Quantity (Unit: Pcs)

Chip/ Reel	400
Carton Box	3,200

8-5. Tearing Off Force



The force for tearing off cover tape is according to the follow table, in the arrow direction under the following conditions.

(Referenced ANSI/EIA-481-D-2008 of 4.11 standard)

Room Temp. (°C)	Room Humidity (%)	Room atm (hPa)	Tearing Speed (mm/min)
5~35	45~85	860~1060	300±10

Tape Size	8 mm	12 to 56 mm	72 mm or Wider
Tearing Off Force (grams)	10~100	10~130	10~150

NOTE: Specifications subject to change without notice. Please check our website for latest information.

Application Notice

1. Storage Conditions

To maintain the solderability of terminal electrodes:

(a) Recommended products should be used within 12 months from the time of delivery.

(b) The packaging material should be kept where no chlorine or sulfur exists in the air.

2. Transportation

(a) Products should be handled with care to avoid damage or contamination from perspiration and skin oils.

(b) Vacuum pick up is strongly recommended for individual components.

(c) Bulk handling should ensure that abrasion and mechanical shock are minimized.